

OFP-MM85QG-SR4C

400G OSFP SR4 Optical Transceiver

Features

- Support 100GBASE per lane in multimode fiber
- Hot-pluggable OSFP Type form factor
- Data rate up to 425Gbps (4x 106.25Gbps)
- Reach up to 100m on MMF(OM4)
- 850nm VCSEL laser and PIN receiver
- High speed I/O electrical interface (400GAUI-4)
- Single MPO-12-APC Receptacle Type
- Compliant to RoHS 6/6
- Compliant to 400G OSFP MSA and CMIS5.0
- Operating case temperature: 0 to +70°C

Absolute Maximum Ratings

Parameters	Symbol	Min	Max	Units	Notes
Case Operating Temperature	T_{OP}	0	70	°C	1,2
Power Supply Voltage	V_{CC}	-0.5	3.6	V	
Storage Temperature Range	T_{ST}	-40	85	°C	1,2
Operating Relative Humidity	RH	5	85	%	1,2,3

Notes:

- 1.Absolute Maximum Ratings are those beyond which damage to the device may occur.
- 2.Between the Recommended Operating conditions and Absolute Maximum ratings, prolonged operation is not intended, and permanent device degradation may occur.
- 3.Non-condensing.

Optical Specification(General)

Parameter	400GBASE-SR4
Application code	400G-SR4
Standard	IEEE Std 802.3db&IEEE Std 802.3ck
Data rate(Gb/s)	425Gb/s

Transmitter Optical Characteristics

Parameter	400GBaSE-SR4	Unit	Note
Signaling rate, each lane (range)	53.125 ± 100 ppm	GBd	
Modulation format	PAM4	-	
Center wavelength (range)	840~860	nm	
RMS spectral width (max)	0.6	nm	1
Average launch power, each lane (max)	4	dBm	
Average launch power, each lane (min)	-4.6	dBm	
Outer Optical Modulation Amplitude (OMA _{outer}), each lane (max)	3.5	dBm	
Outer Optical Modulation Amplitude (OMA _{outer}), each lane (min)for max(TECQ, TDECQ)≤1.8 dBor 1.8 < max(TECQ, TDECQ)≤4.4 dB	- 2.6 -4.4+max (TECQ,TDECQ)	dBm dBm	
Transmitter and dispersion eye closure for PAM4 (TDECQ), each lane (max)	4.4	dB	
Transmitter eye closure for PAM4 (TECQ), each lane (max)	4.4	dB	
Overshoot/undershoot (max)	29	%	
Transmitter power excursion, each lane (max)	2.3	dBm	
Extinction Ratio	2.5	dB	
Transmitter transition time, each lane (max)	17	ps	
Average launch power of OFF transmitter, each lane (max)	-30	dBm	
RIN _{12OMA} (max)	- 132	dB/Hz	
Optical return loss tolerance (max)	14	dB	
Encircled flux	≥86% at 19 nm ≤30% at 4.5um	-	2

Notes:

- 1.RMS spectral width is the standard deviation of the spectrum
- 2.If measured into type A1a.2 or type A1a.3, or A1a.4, 50 μm fiber, in accordance with IEC 61280- 1-4

Receiver Optical Characteristics

Parameter	400GBASE-SR4	Unit	Note
Signaling rate, each lane (range)	53.125 ± 100 ppm	GBd	
Modulation format	PAM4	-	
Center wavelength (range)	840~860	nm	
Damage threshold (min)	5	dBm	1
Average receive power, each lane (max)	4	dBm	
Average receive power, each lane (min)	-6.4	dBm	2
Receive power, each lane (OMA _{outer}) (max)	3.5	dBm	
Receiver reflectance (max)	- 12	dB	
Receiver sensitivity (OMA _{outer}), each lane (max) for TECQ≤1.8 dBfor 1.8<TECQ≤4.4 dB	-4.6 -6.4+TECQ	dBm dBm	
Stressed receiver sensitivity (OMA _{outer}), each lane (max)	-2	dBm	3
Conditions of stressed receiver sensitivity test			4
Stressed eye closure for PAM4 (SECQ), lane under test	4.4	dB	
OMA _{outer} of each aggressor lane	3.5	dBm	

Notes:

- 1.The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level on one lane. The receiver does not have to operate correctly at this input power.
- 2.Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.
- 3.Measured with conformance test signal at TP3 (see 167.8.13) for the BER specified in 167.1.1.
- 4.These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.

Transmitter Electrical Characteristics

Parameter	Reference	Value	Unit	
Signaling rate, each lane (range)	120G.3.4.1	53.125 ± 50 ppm	GBd	
Differential pk-pk input voltage tolerance (min)	120G.5.1	900	mV	
Differential to common-mode return loss (min)	120G.3.3.2	Equation(120G-2)	dB	
Effective return loss, ERL (min)	120G.3.4.3	8.5	dB	
Differential termination mismatch (max)	120G.3.1.3	10	%	
Module stressed input test	120G.3.4.2	See 120G.3.4.2		1
Single-ended voltage tolerance range (min)	120G.5.1	-0.4 to 3.3	V	
DC common-mode voltage (min)	120G.5.1	-350	mV	2
DC common-mode voltage (max)	120G.5.1	2850	mV	2

Notes:

- 1.Meets BER specified in 120G.1.1 References are from IEEE 802.3ck
- 2.DC common-mode voltage generated by the host. Specification includes effects of ground offset voltage.

Receiver Electrical Characteristics

Parameter	Reference	Value	Unit	Note
Signaling rate, each lane (nominal)		53.1251	GBd	1
AC common-mode output voltage (max, RMS)	120G.5.1	17.5	mV	
Differential peak-to-peak output voltage (max) Short mode Long mode	120G.5.1	600 900	mV mv	
Eye height (min)	120G.3.2.2	15	mV	
Vertical eye closure, VEC (max)	120G.3.2.2	12	dB	
Common-mode to differential return loss (min)	120G.3.1.1	Equation (120G- 1)	dB	
Effective return loss, ERL (min)	120G.3.2.3	8.5	dB	
Differential termination mismatch (max)	120G.3.1.3	10	%	
Transition time (min)	120G.3.1.4	8.5	ps	
DC common-mode voltage (min)	120G.5.1	-350	mV	2
DC common-mode voltage (max)	120G.5.1	2850	mV	2

Notes:

- 1.The signaling rate range is derived from the PMD receiver input.
- 2.DC common-mode voltage is generated by the host. Specification includes effects of ground offset voltage.

Electrical Power Supply Characteristics

Parameter	Symbol	Min	Typ.	Max	Units
Power Supply Voltage	VCC1 , VCCTx, VCCRx	3.13	3.30	3.47	V
Power Consumption	PW	-	-	10	W
Power Consumption-LP mode	-	-	-	1.5	W

Notes:The specified characteristics are met within the recommended range of operation. Unless otherwise noted typical data are quoted at nominal voltage and +25°C ambient temperature.

Electrical Pin Definition

Pin	Symbol	Description	Logic	Direction	Plug Sequence	Note
1	GND	Ground			1	
2	TX2p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
3	TX2n	Transmitter Data Inverted	CML-I	Input from Host	3	
4	GND	Ground			1	
5	TX4p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
6	TX4n	Transmitter Data Inverted	CML-I	Input from Host	3	
7	GND	Ground			1	
8	TX6p	Underfined	CML-I	Input from Host	3	
9	TX6n	Underfined	CML-I	Input from Host	3	
10	GND	Ground			1	
11	TX8p	Underfined	CML-I	Input from Host	3	
12	TX8n	Underfined	CML-I	Input from Host	3	
13	GND	Ground			1	
14	SCL	2-wire Serial interface clock	LVC MOS-I/O	Bi-directional	3	Open-Drain with pull up resistor on H
15	VCC	+3.3V Power		Power from Host	2	
16	VCC	+3.3V Power		Power from Host	2	
17	LPWn/PRSn	Low-Power Mode / Module Present	Multi-Level	Bi-directional	3	See pin description for required circuit
18	GND	Ground			1	
19	RX7n	Underfined	CML-O	Output to Host	3	
20	RX7p	Underfined	CML-O	Output to Host	3	
21	GND	Ground			1	
22	RX5n	Underfined	CML-O	Output to Host	3	
23	RX5p	Underfined	CML-O	Output to	3	
24	GND	Ground			1	
25	RX3n	Receiver Data Inverted	CML-O	Output to Host	3	
26	RX3p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
27	GND	Ground			1	
28	RX1n	Receiver Data Inverted	CML-O	Output to Host	3	

29	RX1p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
30	GND	Ground			1	
31	GND	Ground			1	
32	RX2p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
33	RX2n	Receiver Data Inverted	CML-O	Output to Host	3	
34	GND	Ground			1	
35	RX4p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
36	RX4n	Receiver Data Inverted	CML-O	Output to Host	3	
37	GND	Ground			1	
38	RX6p	Underfined	CML-O	Output to Host	3	
39	RX6n	Underfined	CML-O	Output to Host	3	
40	GND	Ground			1	
41	RX8p	Underfined	CML-O	Output to Host	3	
42	RX8n	Underfined	CML-O	Output to Host	3	
43	GND	Ground			1	
44	INT/RSTn	Module Interrupt / Module Reset	Multi-Level	Bi-directional	3	See pin description for required circuit
45	VCC	+3.3V Power		Power from Host	2	
46	VCC	+3.3V Power		Power from Host	2	
47	SDA	2-wire Serial interface data	LVC MOS-I/O	Bi-directional	3	Open-Drain with pull up resistor on Host
48	GND	Ground			1	
49	TX7n	Transmitter Data Inverted	CML-I	Input from Host	3	
50	TX7p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
51	GND	Ground			1	
52	TX5n	Underfined	CML-I	Input from Host	3	
53	TX5p	Underfined	CML-I	Input from Host	3	
54	GND	Ground			1	
55	TX3n	Transmitter Data Inverted	CML-I	Input from Host	3	
56	TX3p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
57	GND	Ground			1	
58	TX1n	Transmitter Data Inverted	CML-I	Input from Host	3	

59	TX1p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
60	GND	Ground			1	

Connector Pad Layout

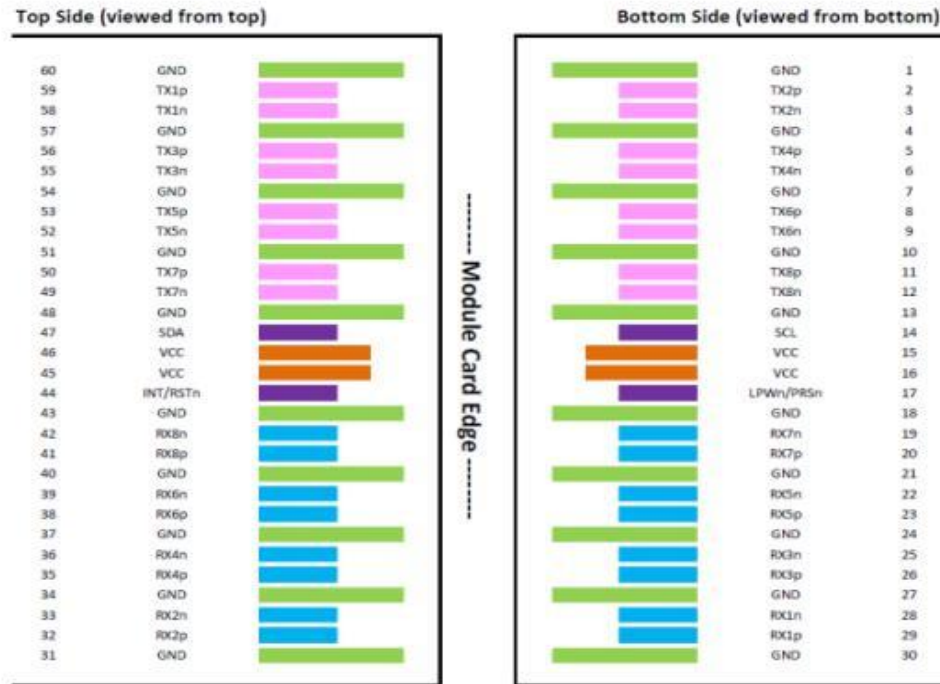


Figure 11-1: OSFP module pinout

Figure 1 OSFP Module contact assignment

Application Notes

Electrical interface: All signal interfaces are compliant with the OSFP REV4.1 MSA specification. The high speed DATA interface is differential AC-coupled internally and can be directly connected to a 3.3V SERDES IC.

High-Speed Signals: The high-speed signals consist of 4 transmit and 4 receive differential pairs identified as TX[4:1]p / TX[4:1]n and RX[4:1]p/RX[4:1]n. These signals can be operated in port configurations of either a single 4-lanes, dual 2-lanes, 4 individual lanes depending on the capability of the host ASIC.

400GAUI-4 mode provides 4 differential lanes using 112G-PAM4 signaling operating at 53.125 GBaud.

This results in 4 lanes of 100Gb/s for a total of 400Gb/s.

The high-speed signals follow the electrical specifications of IEEE802.3bs, IEEE802.3cd, IEEE802.3ck and CEI-56G-VSR-PAM as defined in OIF-CEI-04.0 for 400GAUI-4 mode and IEEE802.3bj, IEEE802.3bm for CAUI-4 mode.

Low-Speed Signals: There are 4 low-speed signals consisting of SCL, SDA, LPWn/PRSn and INT/RSTn. These signals are used for configuration and control of the module by the host. SCL and SDA use 3.3V LVCMOS levels and are bidirectional signals. LPWn/PRSn and INT/RSTn have additional circuitry on the host and module to enable multi-level bidirectional signaling.

Power: +3.3V power is delivered to the module via 4 power pins (VCC). These 4 power pins shall be connected together on the module and also together on the host. Each power pin allows up to 2.5 Amps for a total of 10.0 Amps. This enables a maximum power in excess of 30 Watts.

The specification of the module power is in accordance with methods defined by SFF- 8679 Rev 1.7 section 5.5. There are 8 power classes defined as shown in Table 11-8. All modules in reset or the default low power mode must comply with Power Class 1. High power mode enables the module to draw power up to its advertised power class, and may be conditionally enabled by the host. The host may read the module power class register to know the power class of the module before or after enabling high power mode. The module shall not exceed the power class it identifies for itself.

Transition between low and high power mode is controlled by the M_RSTn (reset) signal, M_LPWn (low power mode) signal and ForceLowPwr bit. The module shall remain in or transition to low power mode when M_LPWn or M_RSTn are asserted or the ForceLowPwr bit is set. While in low power mode, active modules shall also disable transmitters. The module may transition to high power mode once M_RSTn and M_LPWn are deasserted and the ForceLowPwr bit is cleared.

Digital Diagnostic Specification

Parameter	Symbol	Min	Typical	Max	Units	Notes
Transceiver Case Temperature	DMI_Temp	-3		+3	°C	Over operating temp
Supply voltage monitor absolute error	DMI_VCC	-3%		+3%	V	Full operating range
Channel RX power monitor absolute error	DMI_RX	-3		+3	dB	Per channel
Channel Bias current monitor	DMI_Ibias	- 10%		+10%	mA	Per channel
Channel TX power monitor absolute error	DMI_TX	-3		+3	dB	Per channel

Memory Map-5.0

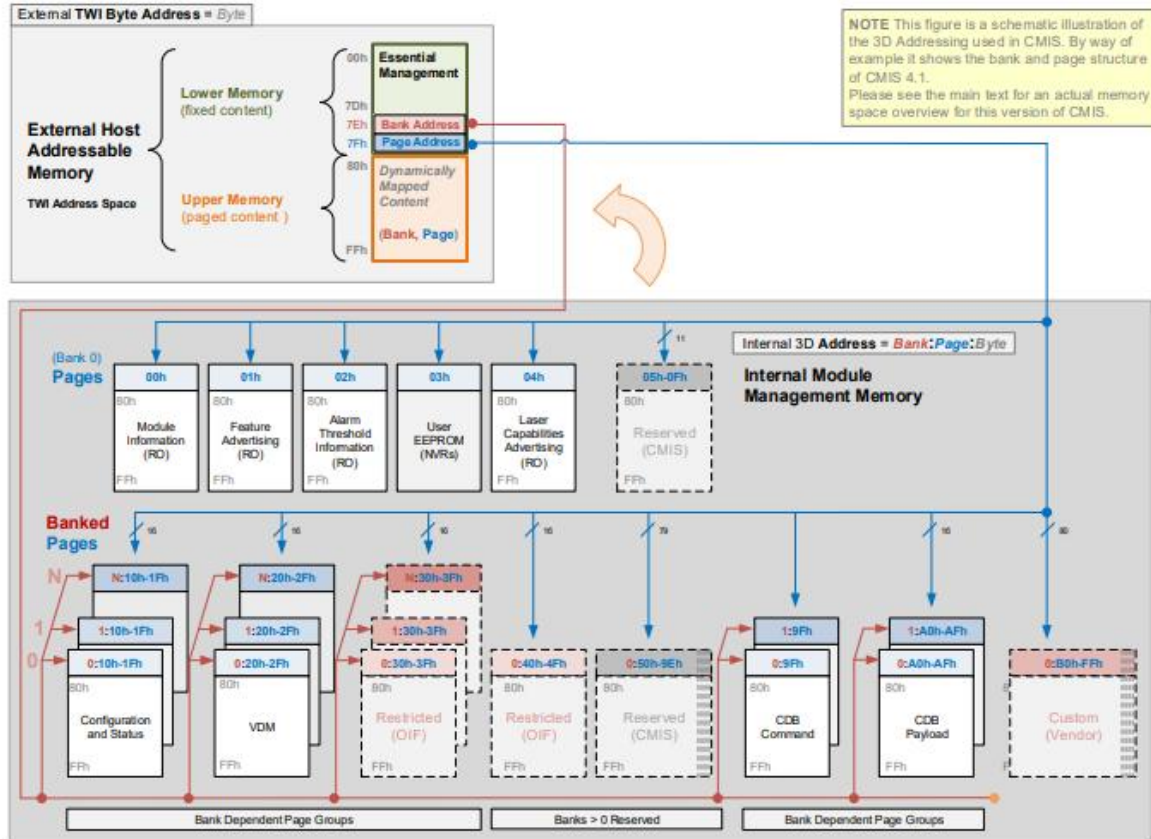


Figure 3 - OSFP Memory Map

OPTICAL INTERFACE LANES AND ASSIGNMENT

The recommended location and numbering of the optical ports for 3 Media Dependent Interfaces (MDI) are shown in Figure 4. The transmit and receive optical lanes shall occupy the positions depicted in Figure 4 when looking into the MDI receptacle with the connector keyway feature on top.

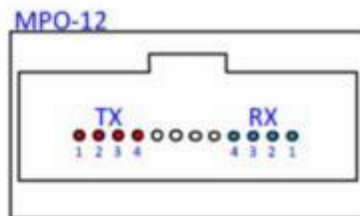


Figure 4 -Optical media dependent interface port assignment

Mechanical Specifications

All dimensions shown are in millimetres.

Tolerances are in accordance with OSFP MSA.

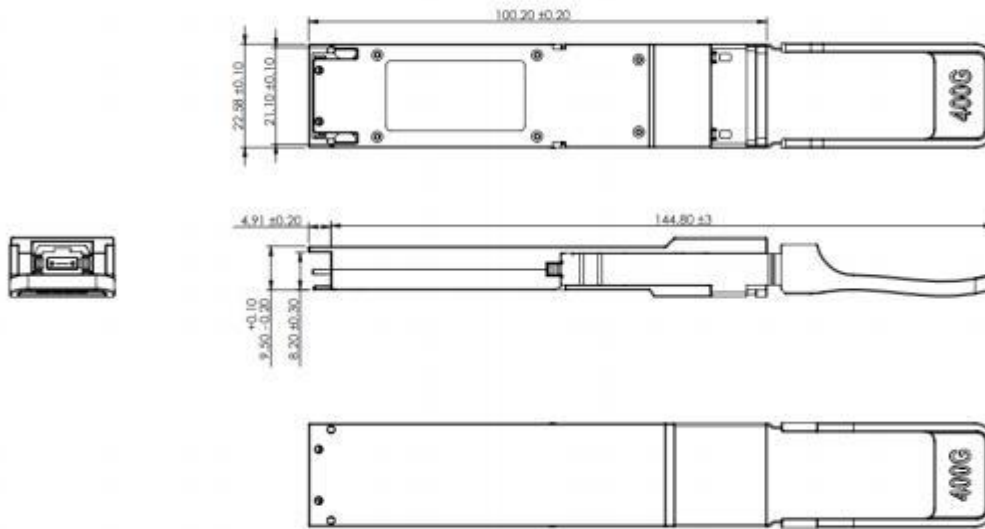


Figure 5 – OSFP Mechanical Specifications

Ordering information

Part Number	Product Description
OFP-MM85QG-SR4C	400Gbps, OSFP SR4 , 850nm, 100m, 0°C~+70°C

For More Information

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